Nicholson, Debbie

From: Drell, Persis S.
Sent: Tuesday, August 17, 2004 5:13 PM
To: Nicholson, Debbie
Subject: FW: Tracker management meeting: Friday 7/21

please post on web site under data on tungsten bonding

From: brez [mailto:alessandro.brez@pi.infn.it]
Sent: Friday, July 23, 2004 8:01 AM
To: Drell, Persis S.
Cc: 'Ronaldo.Bellazzini@pi.infn.it'; 'Luca.Latronico@pi.infn.it'; 'nmenon@stellarsolutions.com'; 'tvenator@pop400.gsfc.nasa.gov'; 'rjohnson@scipp.ucsc.edu'; Rich, David; Klaisner, Lowell
Subject: Re: Tracker management meeting: Friday 7/21

Hi all
the experimental data up to now are:
lap shear strenght of the 3m2216 measured as fos ASTM

T ^{o}C	Shear str. MPa
20	16.7
35	9.2
55	7.1
70	4.1
85	3.6

Pell strenght kapton-W samples:
sand paper, roughness 0.45um, peel strenght 1.5N/mm, adhesive layer left on kapton
sand blasted, roughness 0.5um, peel strenght 2.7N/mm, adhesive layer left on kapton 2 cases/3, in one sample part of the adhesive is on W)
sand blasted, roughness 1um, peel strenght not measured (samples broken before peel), adhesive layer left on tungsten
The peel strenght at 1um roughness will be measured next week (test ingeneer absent now)
Sandro

Drell, Persis S. wrote:

> Dear All,
>
> I have assembled a partial list of items to discuss at our 7/21 telecon
>
> - Schedule Update
> - Progress on critical items
> - Bias circuit bonding tests and results
>
> For the last item, I would like to emphasize a management level discussion on how we are moving forward to address the issues in the bias circuit bonding. I have attached a document that summarizes what I know about the existing analyses that have been done on thermally induced stresses in the kapton-tungsten joint. I do not propose we discuss this document. It is for reference. If there are other analyses that we feel should be done it would appropriate to discuss

how to move forward with them.

I look forward to talking with you

Persis

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A call in number has been set up:
9:00 a.m. PST/ 16:00 Italian time
510-665-5437
Meeting ID: 4331